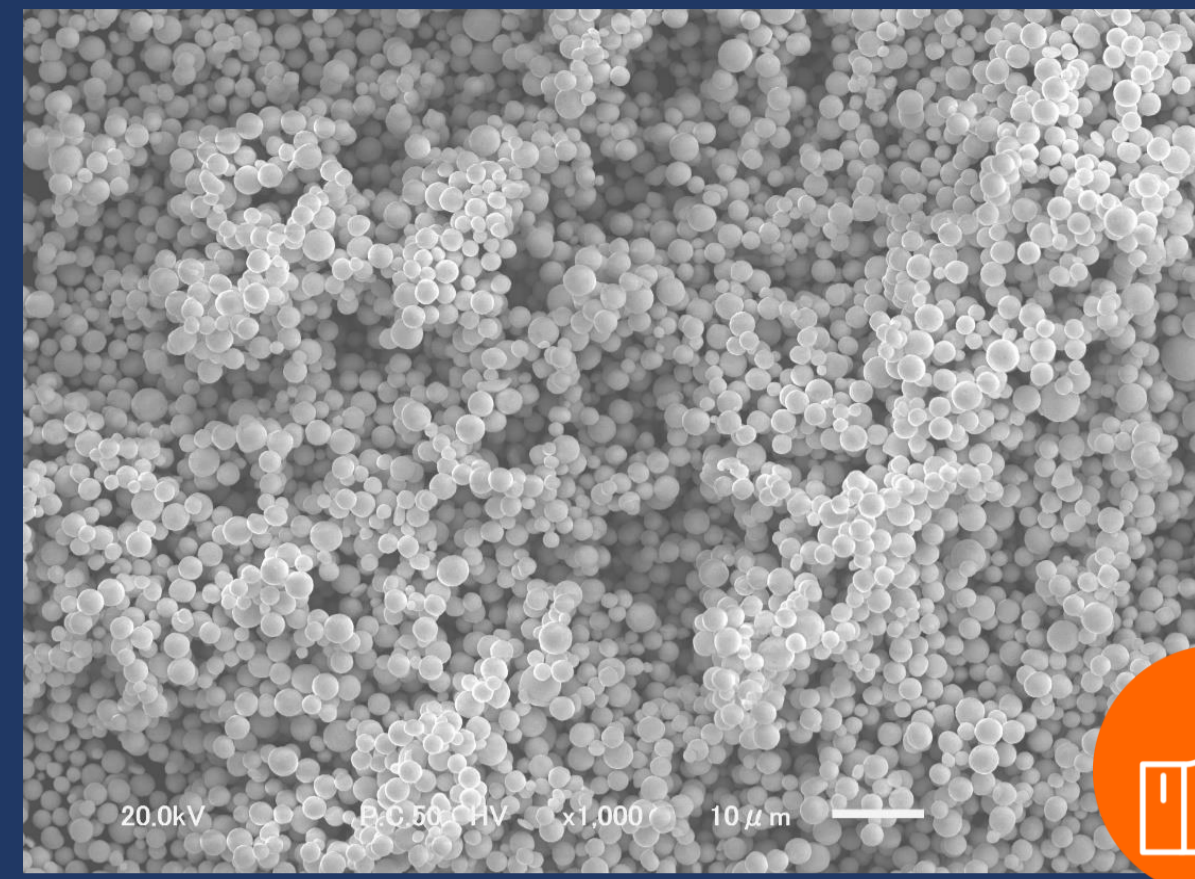
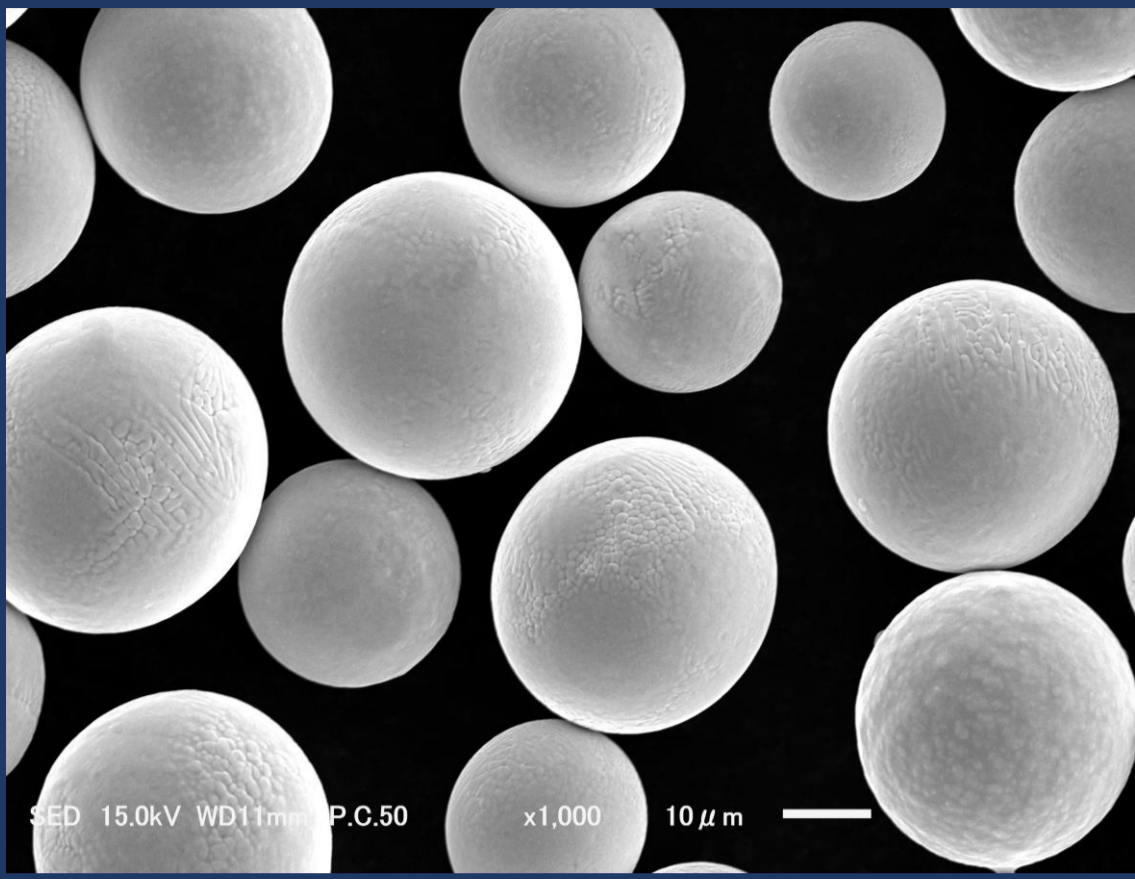


超微細粉末 Type 9 錫膏

Super Fine Powder Type 9 Solder Paste

Type 4
20-38 μm



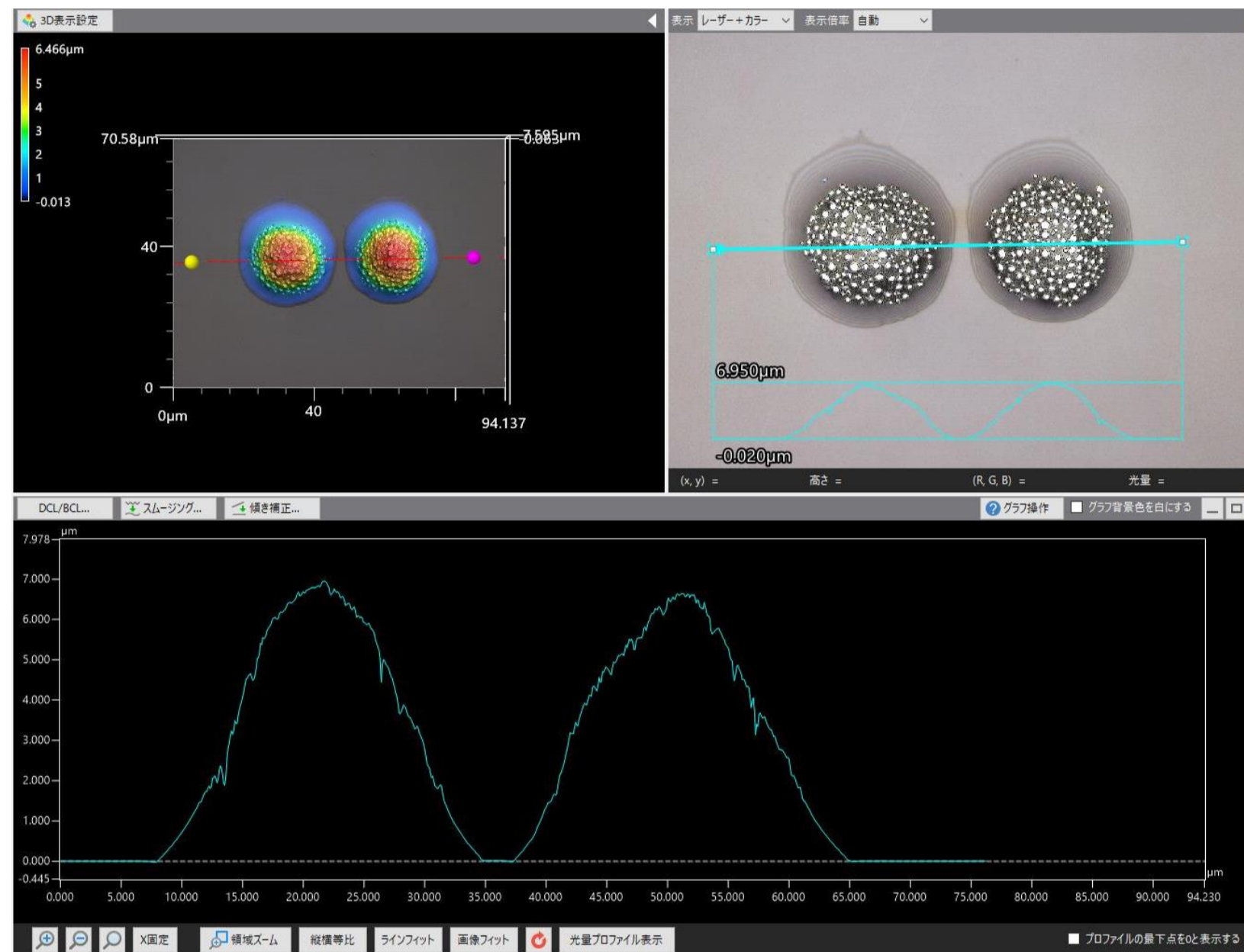
Type 9
1-5 μm



適用各種微量供給製程

即使是超微量點錫也有良好的印刷性！

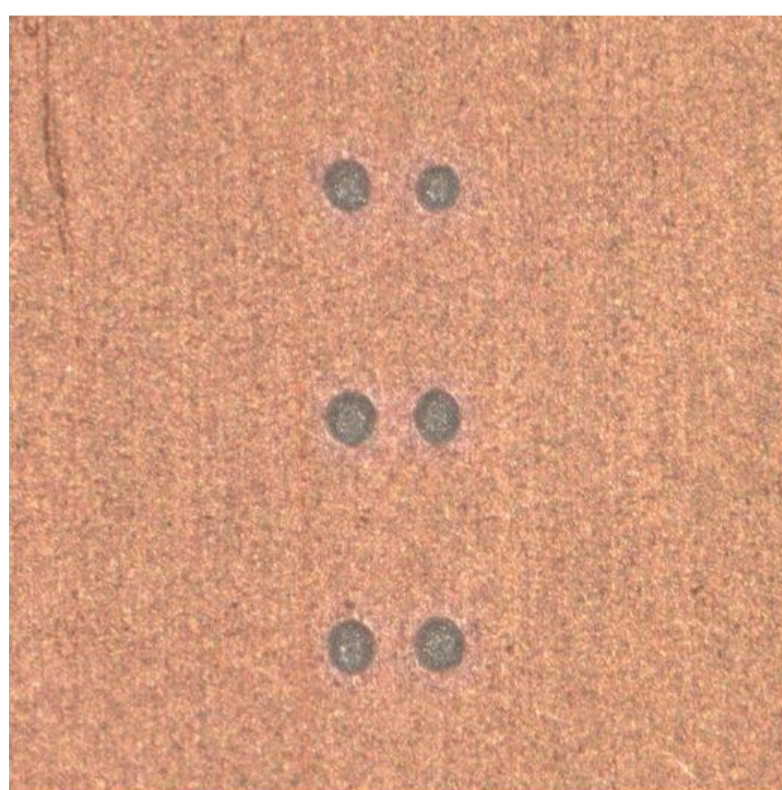
- 開口大小：15 μm
- 鋼板厚度：12 μm



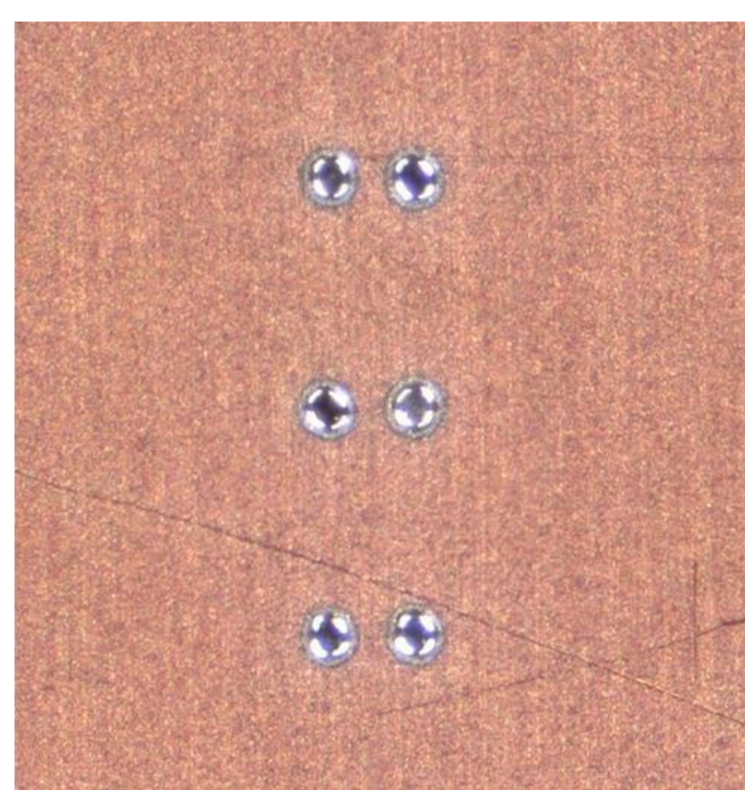
水洗型助焊劑也可使用

水洗型錫膏在微量印刷下也能保有良好熔融及洗淨性

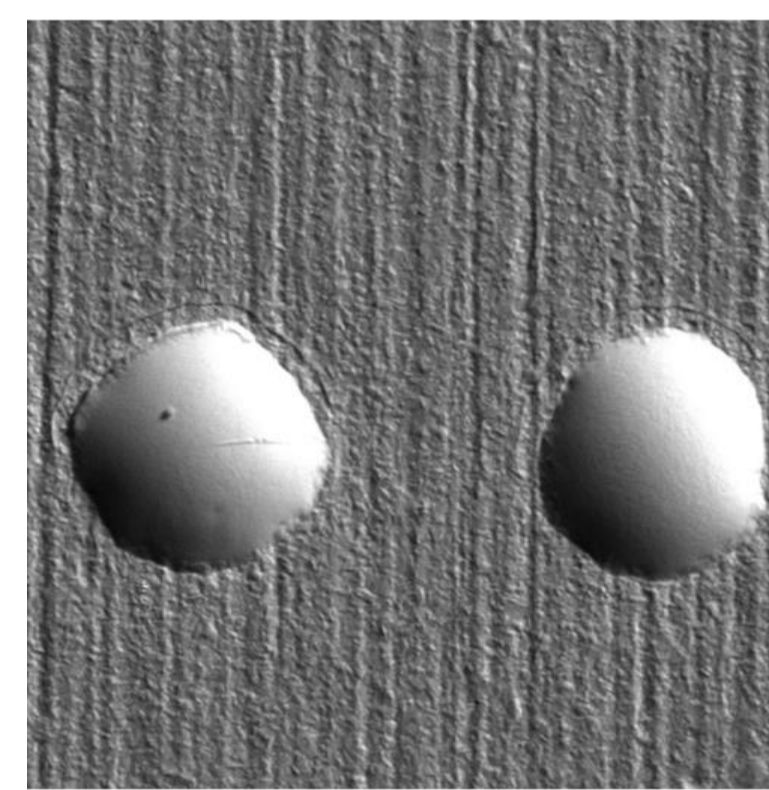
印刷後



加熱後



洗淨後



可用於點錫製程

Air Dispense 氧氣濃度100 ppm以下

可確保1萬點連續穩定點錫

約 $\phi 70\mu\text{m}$

